

INTERNATIONAL STANDARD

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**Information technology –
Small computer system interface (SCSI) –**

**Part 112:
Parallel Interface-2 (SPI-2)**

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Contents

	Page
Introduction	xiv
1 Scope	1
2 Normative references	2
2.1 Normative references	2
2.2 Approved references	2
2.3 References under development	3
3 Definitions, symbols, abbreviations, and conventions	3
3.1 Definitions	3
3.2 Symbols and abbreviations	11
3.3 Keywords	11
3.4 Conventions	12
3.5 Notation for Procedures and Functions	13
4 General	14
4.1 Overview	14
4.1.1 Data transfer modes	14
4.1.2 Cables, Connectors, Signals, Transceivers	14
4.1.3 Physical architecture of bus	14
4.1.4 Physical topology details and definitions	15
4.1.5 Bus loading	17
4.1.6 Termination requirements	18
4.1.7 Device Addressing	18
4.1.8 Protocol	18
5 SCSI parallel interface connectors	21
5.1 SCSI parallel interface connectors overview	21
5.2 Nonshielded connector	21
5.2.1 Nonshielded connector alternative 1 - A cable	21
5.2.2 Nonshielded connector alternative 2 - A cable	21
5.2.3 Nonshielded connector alternative 3 - P cable and Q cable	21
5.2.4 Nonshielded connector alternative 4	22
5.3 Shielded connector	27
5.3.1 Shielded connector alternative 1 - A cable	28
5.3.2 Shielded connector alternative 2 - A cable	28
5.3.3 Shielded connector alternative 3 - P cable and Q cable	28
5.3.4 Shielded connector alternative 4 - P cable and Q cable	28
5.4 Connector contact assignments	37
5.4.1 SE assignments	38
5.4.2 Differential connector contact assignments	42
6 SCSI bus interconnect	49
6.1 SCSI bus interconnect overview	49
6.2 SCSI bus cables	49
6.3 Interconnect characteristics for signals	50
6.4 Decoupling characteristics for TERMPWR and TERMPWRQ lines	52
6.5 Connection requirements for RESERVED lines	53
6.6 Cables used with SE transceivers	53
6.6.1 SE ground offset	54
6.7 Cables used with differential transceivers	54
6.7.1 HVD stub length and spacing	54
6.7.2 LVD stub length and spacing	55
7 SCSI parallel interface electrical characteristics	56
7.1 SCSI parallel interface electrical characteristics overview	56
7.2 SE alternative	57

7.2.1 SE termination	57
7.2.2 SE output characteristics	57
7.2.3 SE input characteristics	60
7.2.4 SE input and output characteristics	61
7.3 LVD alternative	62
7.3.1 LVD termination	62
7.3.2 LVD driver characteristics	66
7.3.3 LVD receiver characteristics	66
7.3.4 LVD capacitive loads	67
7.3.4.1 Management of LVD release glitches	69
7.3.5 SE/HVD transmission mode detection	69
7.3.5.1 LVD DIFFSENS driver	70
7.3.5.2 LVD DIFFSENS receiver	70
7.4 LVD/MSE multimode alternative	72
7.4.1 LVD/MSE multimode termination	72
7.4.2 LVD/MSE multimode transceiver characteristics	73
7.4.3 Power for LVD/MSE multimode transceivers	74
7.4.4 Ground drivers	74
7.5 HVD alternative	75
7.5.1 HVD termination	75
7.5.2 HVD output characteristics	76
7.5.3 HVD input characteristics	78
7.5.4 SE driver protection	79
7.6 Terminator power	80
8 SCSI bus signals	82
8.1 SCSI bus signals overview	82
8.2 Signal descriptions	83
8.3 Parity checking rules	84
8.4 Signal states	84
8.4.1 SE	84
8.4.2 Differential	85
8.5 OR-tied signals	86
8.6 Signal sources	86
9 SCSI parallel bus timing	88
9.1 SCSI parallel bus timing values	88
9.2 Timing description	89
9.2.1 Arbitration delay	89
9.2.2 Bus clear delay	90
9.2.3 Bus free delay	90
9.2.4 Bus set delay	90
9.2.5 Bus settle delay	90
9.2.6 Cable skew	90
9.2.7 Data release delay	90
9.2.8 Disconnection delay	90
9.2.9 Power on to selection	90
9.2.10 Receive assertion period	90
9.2.11 Receive hold time	91
9.2.12 Receive negation period	91
9.2.13 Receive setup time	91
9.2.14 Receive period tolerance	91
9.2.15 Reset hold time	91
9.2.16 Reset to Selection	91
9.2.17 Selection abort time	91
9.2.18 Selection time-out delay	91
9.2.19 Signal Timing Skew	91
9.2.20 System deskew delay	91
9.2.21 Transmit assertion period	92
9.2.22 Transmit hold time	92
9.2.23 Transmit negation period	92

9.2.24 Transmit setup time	92
9.2.25 Transmit period tolerance	92
9.3 Measurement points	92
9.3.1 SE fast-10 data transfer rates	92
9.3.2 SE fast-20 data transfer rates	93
9.3.3 LVD	94
9.3.4 HVD	95
9.4 Setup and hold timings	96
9.4.1 Fast-10 data transfer rates	96
9.4.2 Fast-20 data transfer rates	98
9.4.3 Fast-40 data transfer rates	100
10 Removal and insertion of SCSI devices	102
10.1 Removal and insertion of SCSI devices overview	102
10.2 Case 1 - Power-off during removal or insertion	102
10.3 Case 2 - RST signal asserted continuously during removal or insertion	102
10.4 Case 3 - Current I/O processes not allowed during insertion or removal	102
10.5 Case 4 - Current I/O process allowed during insertion or removal	103
11 Logical characteristics	104
11.1 SCSI bus phases	104
11.1.1 SCSI bus phase overview	104
11.1.2 BUS FREE phase	104
11.1.3 Unexpected bus free	104
11.1.4 ARBITRATION phase	105
11.1.5 SELECTION phase	105
11.1.6 SELECTION time-out procedure	106
11.1.7 RESELECTION phase	106
11.1.7.1 RESELECTION phase overview	106
11.1.7.2 RESELECTION	106
11.1.7.3 RESELECTION time-out procedure	107
11.1.8 Information transfer phases	107
11.1.8.1 Information transfer phases overview	107
11.1.8.2 Asynchronous information transfer	108
11.1.8.3 Synchronous data transfer	108
11.1.8.4 Wide data transfer	109
11.1.9 COMMAND phase	111
11.1.10 Data phase	111
11.1.10.1 Data phase overview	111
11.1.10.2 DATA IN phase	111
11.1.10.3 DATA OUT phase	111
11.1.11 STATUS phase	111
11.1.11.1 STATUS phase overview	111
11.1.11.2 STATUS phase exception condition handling	111
11.1.12 Message phase	111
11.1.12.1 Message phase overview	111
11.1.12.2 MESSAGE IN phase	111
11.1.12.3 MESSAGE IN phase exception condition handling	112
11.1.12.4 MESSAGE OUT phase	112
11.1.12.5 MESSAGE OUT phase exception condition handling	112
11.1.13 Signal restrictions between phases	112
11.2 SCSI bus conditions	113
11.2.1 SCSI bus conditions overview	113
11.2.2 Attention condition	113
11.2.3 Hard reset	113
11.2.4 Reset events	114
11.2.5 Transceiver mode change reset event	114
11.3 SCSI bus phase sequences	114
11.4 SCSI pointers	115
11.5 SCSI interlocked protocol messages	115
11.5.1 SCSI interlocked protocol messages overview	115

11.5.2 Message protocols and formats	116
11.5.2.1 Message protocol rules	116
11.5.2.2 Message formats	116
11.5.2.2.1 Message formats overview	116
11.5.2.2.2 One-byte messages	117
11.5.2.2.3 Two-byte messages	117
11.5.2.2.4 Extended messages	117
11.5.3 Link control messages	118
11.5.3.1 Link control message codes	118
11.5.3.2 CONTINUE TASK	118
11.5.3.3 DISCONNECT	119
11.5.3.4 IDENTIFY	119
11.5.3.5 IGNORE WIDE RESIDUE	120
11.5.3.6 INITIATOR DETECTED ERROR	121
11.5.3.7 MESSAGE PARITY ERROR	121
11.5.3.8 MESSAGE REJECT	121
11.5.3.9 MODIFY DATA POINTER	122
11.5.3.10 NO OPERATION	122
11.5.3.11 RESTORE POINTERS	122
11.5.3.12 SAVE DATA POINTER	122
11.5.3.13 SYNCHRONOUS DATA TRANSFER REQUEST	122
11.5.3.13.1 SYNCHRONOUS DATA TRANSFER REQUEST overview	122
11.5.3.13.2 Target initiated SDTR negotiation	125
11.5.3.13.3 Initiator initiated SDTR negotiation	125
11.5.3.14 TARGET TRANSFER DISABLE	125
11.5.3.15 TASK COMPLETE	126
11.5.3.16 WIDE DATA TRANSFER REQUEST	126
11.5.3.16.1 WIDE DATA TRANSFER REQUEST overview	126
11.5.3.16.2 Target initiated WDTR negotiation	128
11.5.3.16.3 Initiator initiated WDTR negotiation	128
11.5.4 Task attribute messages	129
11.5.4.1 Task attribute messages overview	129
11.5.4.2 ACA	130
11.5.4.3 HEAD OF QUEUE	130
11.5.4.4 LINKED COMMAND COMPLETE	131
11.5.4.5 LINKED COMMAND COMPLETE (WITH FLAG)	131
11.5.4.6 ORDERED	131
11.5.4.7 SIMPLE	131
11.5.5 Task management messages	132
11.5.5.1 Task management message codes	132
11.5.5.2 ABORT TASK	132
11.5.5.3 ABORT TASK SET	132
11.5.5.4 CLEAR ACA	133
11.5.5.5 CLEAR TASK SET	133
11.5.5.6 LOGICAL UNIT RESET	133
11.5.5.7 TARGET RESET	133
11.5.5.8 TERMINATE TASK	133
11.6 Command processing considerations and exception conditions	133
11.6.1 Command processing considerations and exception conditions overview	133
11.6.2 Asynchronous event notification	134
11.6.3 Incorrect initiator connection	134
11.6.4 Unexpected reselection	135
11.7 Use of disconnect-reconnect page parameters	135
11.8 SCSI parallel interface services	136
11.8.1 SCSI parallel interface services overview	136
11.8.2 Procedure terms	136
11.8.3 Application client SCSI command services	138
11.8.3.1 Application client SCSI command services procedure call	138
11.8.3.2 Send SCSI command service	139
11.8.4 Device server SCSI command services	139
11.8.4.1 Device server SCSI command services procedure call	139

11.8.4.2 Data-in delivery service	139
11.8.4.3 Data-out delivery service	140
11.8.5 Task management services	140
11.8.5.1 Task management services procedure call	140
11.8.5.2 Task management function service	140
11.8.5.2.1 Task management function service overview	140
11.8.5.2.2 ABORT TASK	140
11.8.5.2.3 ABORT TASK SET	141
11.8.5.2.4 CLEAR ACA	141
11.8.5.2.5 CLEAR TASK SET	141
11.8.5.2.6 LOGICAL UNIT RESET	141
11.8.5.2.7 RESET SERVICE DELIVERY SUBSYSTEM	141
11.8.5.2.8 TARGET RESET	141
11.8.5.2.9 TERMINATE TASK	141
11.8.5.2.10 WAKEUP	141
Annex A Additional requirements for LVD SCSI drivers and receivers	142
A.1 System level requirements	142
A.2 Driver requirements	142
A.2.1 Differential output voltage, VS	143
A.2.2 Offset (common-mode output) voltage, VCM	145
A.2.3 Short-circuit currents, IO-S and IO+S	146
A.2.4 Open-circuit output voltages, $V_{O-(OC)}$ and $V_{O+(OC)}$	147
A.2.5 Output signal waveform	147
A.2.6 Dynamic output signal balance, VCM(PP)	149
A.3 Receiver characteristics	150
A.3.1 Receiver steady state input voltage requirements	151
A.3.2 Compliance test	151
A.3.3 Receiver setup and hold times	152
A.4 Transceiver characteristics	152
A.4.1 Transceiver output/input currents, I_{IL} and I_{IL+L}	152
A.4.2 Transceiver maximum input voltages	153
Annex B SCSI configured automatically (SCAM)	154
B.1 Model	154
B.2 Glossary	154
B.3 SCAM requirements	155
B.3.1 Configuration requirements	155
B.3.2 Timing requirements	155
B.3.2.1 SCAM tolerant power-on to selection delay	156
B.3.2.2 SCAM tolerant reset to selection delay	156
B.3.2.3 SCAM tolerant selection response time	156
B.3.2.4 SCAM unassigned ID selection response delay	156
B.3.2.5 SCAM power-on to SCAM selection delay	156
B.3.2.6 SCAM reset to SCAM selection delay	156
B.3.2.7 SCAM selection response time	156
B.3.2.8 Recommended SCAM selection response time	156
B.3.2.9 Wide arbitration time	156
B.3.3 Device requirements	157
B.3.3.1 SCAM tolerant target	157
B.3.3.2 Level 1 SCAM initiator	157
B.3.3.3 Level 1 SCAM target	157
B.3.3.4 Level 2 SCAM initiator	158
B.3.3.5 Level 2 SCAM target	158
B.4 SCAM protocol	159
B.4.1 Initiation	159
B.4.1.1 Transfer cycles	159
B.4.1.2 Wired-OR glitch filtering	160
B.4.1.3 Isolation stage	161

B.4.1.4 Function sequences	164
B.4.1.4.1 Isolate function	165
B.4.1.4.2 Isolate and set priority flag function	166
B.4.1.4.3 Configuration process complete function	166
B.4.1.4.4 Dominant initiator contention function	167
B.5 SCAM operations	167
B.5.1 SCAM initiator	167
B.5.1.1 Dominant SCAM initiator	168
B.5.1.1.1 SCSI ID categorization	168
B.5.1.1.2 SCSI ID assignment	168
B.5.1.2 Subordinate SCAM initiator	168
B.5.2 Level 1 SCAM target	169
B.5.3 Level 2 SCAM target	170
Annex C SCSI bus fairness	172
C.1 Model	172
C.2 Determining fairness by monitoring prior bus activity	172
C.3 Fairness algorithm	172
C.4 Additional comments	173
Annex D SCA-2 Connector pinouts	175
D.1 SCA-2 Signal Definitions	175
D.1.1 VOLTAGE and GROUND signals	175
D.1.2 CHARGE signals	175
D.1.3 SPINDLE SYNC	176
D.1.4 ACTIVE LED OUT	177
D.1.5 Motor Start Controls	177
D.1.6 SCSI ID Selection	178
D.1.7 MATED Signals	179
D.1.7.1 MATED 2/Drive Side	179
D.1.7.2 MATED 2/Backplane Side	180
D.1.7.3 MATED 1/Drive Side	180
D.1.7.4 MATED 1/Backplane Side	180
Annex E Interconnecting buses of different widths	182
Annex F Cabling and cable measurement method recommendations	185
F.1 Cabling	185
F.2 Cable measurement	185
F.2.1 Impedance, TDR, single-ended	185
F.2.2 Impedance, TDR, differential	185
F.2.3 Attenuation, differential	186
F.2.4 Velocity (propagation delay) and skew	186
Annex G Transmission line considerations for fast-20 data transfer rates	187
Annex H Measuring SE pin capacitance	190
Annex I SCSI ICONS	191
Annex J Example of HVD terminator network	193
Annex K SCSI-3 to SCSI-2 terminology mapping	194
Annex L SCA-2 Unshielded Connections	195
L.1 Definitions and Conventions	196
L.1.1 Definitions	196

L.2 General Description	198
Annex M VHDCI Shielded Configurations	200
M.1 Definitions and Conventions	200
M.1.1 Definitions	200
M.2 General Description	202

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ISO/IEC 14776-112:2002
<https://standards.iteh.ai/catalog/standards/sist/8da861fb-e87b-45c3-876d-119319188257/iso-iec-14776-112-2002>

Tables

	Page
1 Transceiver/speed support map	14
2 Cross-reference to A cable contact assignments	37
3 SE contact assignments - A cable	38
4 SE contact assignments - P cable	39
5 SE contact assignments - Q cable	40
6 SE contact assignments - nonshielded alternative 4 connector	41
7 LVD contact assignments - A cable	42
8 LVD contact assignments - P cable	43
9 LVD contact assignments - Q cable	44
10 HVD contact assignments - A cable	45
11 HVD contact assignments - P cable	46
12 HVD contact assignments - Q cable	47
13 HVD and LVD contact assignments - nonshielded alternative 4 connector	48
14 Recommended minimum conductor size	50
15 SE characteristic impedance of cable at maximum indicated data transfer rate	51
16 Differential characteristic impedance of cable at indicated data transfer rate	52
17 SE maximum distance between terminators	53
18 Differential maximum distance between terminators	54
20 Minimum stub connection spacing rules for HVD SCSI devices	55
19 HVD stub length and spacing requirements	55
21 Minimum stub connection spacing rules for LVD SCSI devices	55
22 Electrical input requirements at the device connector	56
23 Input current requirements at the device connector for lines not being driven by the device	57
24 SE steady state output voltage characteristics	58
25 SE input voltage characteristics	61
26 SE input and output electrical characteristics	62
27 I-V requirements for LVD impedance, common mode impedance, and V_{BIAS} tests	64
28 Values for LVD termination balance test	65
29 Values for LVD capacitive loads	68
30 Glitch management requirements for devices using LVD drivers	69
31 LVD DIFFSENS driver specifications	70
32 DIFFSENS receiver operating requirements	71
33 I-V requirements for HVD impedance and common mode impedance tests	76
34 Values for HVD termination balance test	76
35 HVD output voltage characteristics	77
37 Values for HVD capacitive loads	79
36 HVD input voltage characteristics	79
38 Terminator power characteristics at the terminator	81
39 Arbitration priorities by SCSI ID	83
40 Parity checking rules	84
41 Signal sources	87
42 SCSI bus timing values	89
43 Information transfer phases	108
44 Wide SCSI byte order	110
45 Message format	117
46 Extended message format	117
47 Link control message codes	118
48 IDENTIFY message format	119
49 IGNORE WIDE RESIDUE message format	120
50 IGNORE field definition	121
51 MODIFY DATA POINTER message format	122
52 SYNCHRONOUS DATA TRANSFER message format	123
53 TRANSFER PERIOD FACTOR field	123
54 SDTR messages implied agreements	124
55 WIDE DATA TRANSFER message format	126
56 WDTR messages implied agreements	128
57 Task attribute message codes	130
58 ACA message format	130
59 HEAD OF QUEUE message format	130

60 ORDERED message format	131
61 SIMPLE message format	131
62 Task management message codes	132
63 DATA TRANSFER DISCONNECT CONTROL	136
64 SCSI Parallel Interface-2 Standard terms mapped to terms from other SCSI-3 standards	136
65 Procedure terms	138
66 Processing of send SCSI command service procedure	139
67 Processing of data-in delivery service procedure	140
68 Processing of data-out delivery service procedure	140
A.1 System level requirements	142
A.2 Driver steady-state test limits and conditions	143
A.3 Driver switching test circuit parameters	148
A.4 Dynamic output balance limits	150
A.5 Receiver steady state input voltage ranges	151
A.6 Receiver minimum and maximum input voltages.	151
B.1 SCAM timing values	155
B.2 Transfer cycle conditions	162
B.3 Identification string	163
B.4 Type code	163
B.5 MAXIMUM ID CODE	163
B.6 ID VALID	164
B.7 Function codes	165
B.8 Action codes	166
B.9 Dominance preference code	167
D.1 Voltage specification limits	175
D.2 Charge supply to SCSI device	176
D.3 Output characteristics of drive 'ACTIVE LED OUT signal	177
D.4 Definition of motor start controls	178
D.5 Electronic requirements for input controls	178
D.6 SCSI device ID selection signals	179
K.1 SPI-2 to SCSI-2 terminology mapping	194

[ISO/IEC 14776-112:2002](https://standards.iteh.ai/catalog/standards/sist/8da861fb-e87b-45c3-876d-119319188257/iso-iec-14776-112-2002)

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Figures

	Page
1 General Structure of SCSI	2
2 Differential SCSI bus	15
3 SE SCSI bus	15
4 SCSI bus topology details	17
5 SCSI Parallel Interface service reference mode	19
6 Model for a four step confirmed services	19
7 Model for a two step confirmed services	20
8 50/68-contact alternative 1/alternative 3 nonshielded SCSI device connector	23
9 50/68-contact alternative 1/alternative 3 nonshielded mating connector	24
10 50-contact alternative 2 nonshielded SCSI device connector (A cable)	25
11 50-contact alternative 2 nonshielded mating connector (A cable)	26
12 80-contact alternative 4 nonshielded SCSI device connector (P cable)	27
13 80-contact alternative 4 nonshielded contact positions	27
14 50-contact alternative 1 shielded SCSI device connector (A cable)	29
15 50-contact alternative 1 shielded mating connector (A cable)	30
16 50-contact alternative 2 shielded SCSI device connector (A cable)	31
17 50-contact alternative 2 shielded mating connector (A cable)	32
18 68-contact alternative 3 shielded SCSI device connector (P cable/Q cable)	33
19 68-contact alternative 3 shielded mating connector (P cable/Q cable)	34
20 68-contact alternative 4 shielded SCSI device connector (P cable/Q cable)	35
21 68-contact alternative 4 shielded contact positions (P cable/Q cable)	36
22 Terminator decoupling example	53
23 Active negation current vs. voltage	59
24 SE A.C. test circuit	60
25 Differential SPI-2 bus terminator	62
26 Test circuit for terminator differential impedance	63
27 Termination I-V characteristics for differential and common mode impedance tests	63
28 Test circuit for termination common mode impedance test	64
29 Termination balance test configuration	65
30 Termination balance test data definition	65
31 LVD transceiver architecture	66
32 LVD receiver example	67
33 Capacitive loads	68
34 LVD DIFFSENS driver signal definitions	70
35 DIFFSENS receiver function	71
36 LVD DIFFSENS receiver example	72
37 Multimode terminator architecture	73
38 Multimode transceiver architecture	74
39 HVD test circuit	78
40 SE driver protection circuit	80
41 Voltage and current definitions	85
42 Signaling sense	86
43 Fast-10 SE timing measurement points	93
44 Fast-20 SE timing measurement points	94
45 LVD timing measurement points	95
46 HVD timing measurement points	96
47 Fast-10 setup and hold times for SE applications	97
48 Fast-10 setup and hold timing for HVD applications	97
49 Fast-20 setup and hold times for SE applications	99
50 Fast-20 setup and hold timing for HVD applications	99
51 Fast-40 System setup and hold timings (all times in ns)	101
52 Phase sequences	115
A.1 Differential steady-state output voltage test circuit	144
A.2 Domain for driver assertion and negation levels	145
A.3 Driver offset steady-state voltage test circuit	146
A.4 Common mode output voltage test	146
A.5 Driver short-circuit test circuit	147
A.6 Open-circuit output voltage test circuit	147
A.7 Differential output switching voltage test circuit	148

A.8 Driver output signal waveform	149
A.9 Driver offset switching voltage test circuit	150
A.10 Receiver input voltage threshold test circuit	152
A.11 Transceiver off-state output current test circuit	153
B.1 Transfer cycles	160
B.2 Level 1 SCAM target states	169
B.3 Level 2 SCAM target states	170
D.1 Sample circuit for mated indications	181
E.1 Interconnecting single-ended A and P cables	183
E.2 Interconnecting HVD A and P cables	184
F.1 Differential impedance measurement	186
G.1 Minimum device spacing versus bus and device capacitance	189
I.1 SE icon for SCSI	191
I.2 LVD icon for SCSI	191
I.3 SE/LVD multimode icon for SCSI	192
I.4 HVD icon for SCSI	192
J.1 Example of termination network for HVD devices	193
L.1 Mating side gender definition	198
L.2 Contact positioning architecture	199
M.1 Mating side gender definition	202

iTeh STANDARD PREVIEW (standards.iteh.ai)

ISO/IEC 14776-112:2002

<https://standards.iteh.ai/catalog/standards/sist/8da861fb-e87b-45c3-876d-119319188257/iso-iec-14776-112-2002>

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SMALL COMPUTER SYSTEM INTERFACE (SCSI) –
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ISO/IEC 14776-112 is intended to be used in conjunction with ISO/IEC 14776-311¹. The resulting interface facilitates the interconnection of computers and intelligent peripherals and thus provides a common interface standard for both system integrators and suppliers of intelligent peripherals.

Annexes A, B, C and D form an integral part of this standard.

Annexes E, F, G, H, I, J, K, L and M are for information only.

¹ Under consideration.